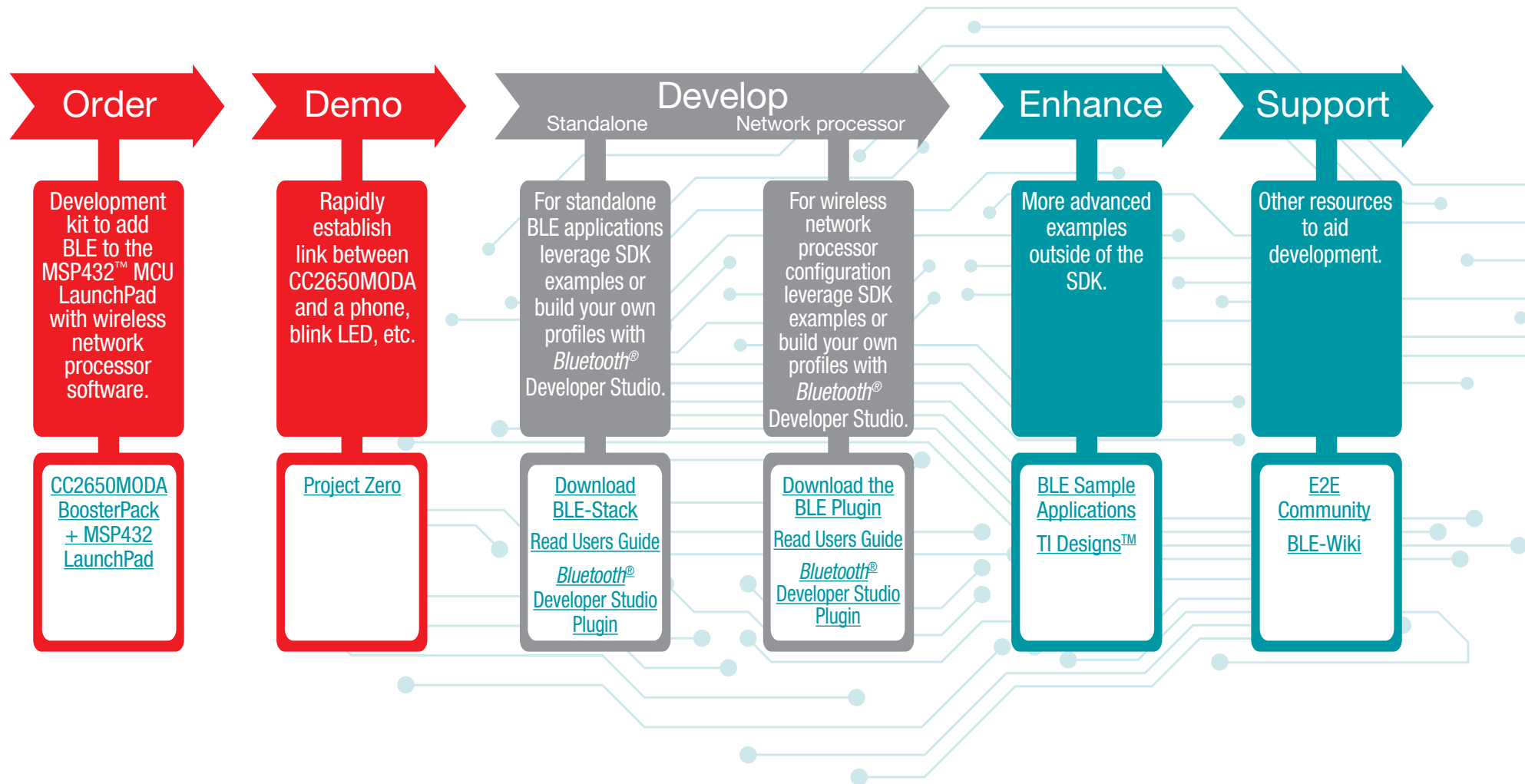


Getting started with *Bluetooth*[®] low energy CC2650MODA for IAR users

Pre-certified Bluetooth low energy module, Bluetooth 4.2 compliant



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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